

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Cheng-Yi Liu et al.

Title: THINNED DIE INTEGRATED CIRCUIT PACKAGE

Docket No.: 884.793US1

Filed: January 7, 2002

Examiner: Mai-Huong Tran

Serial No.: 10/036,389

Due Date: September 10, 2004

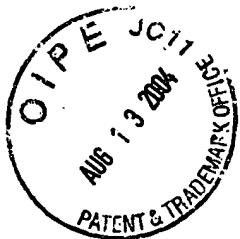
Group Art Unit: 2818

**MS AF**

Commissioner for Patents

P.O. Box 1450

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- A return postcard.  
 Response Under 37 CFR 1.116--EXPEDITED PROCEDURE (10 Pages).

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Customer Number 21186

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EXPEDITED PROCEDURE - EXAMINING GROUP 2818

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2818

S/N 10/036389

PATENT

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Applicant:	Cheng-Yi Liu et al.	Examiner:	Mai-Huong Tran
Serial No.:	10/036389	Group Art Unit:	2818
Filed:	January 7, 2002	Docket No.:	884.793US1
Title:	THINNED DIE INTEGRATED CIRCUIT PACKAGE		
Assignee:	Intel Corporation	Customer No:	21186

**RESPONSE UNDER 37 CFR § 1.116**

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This responds to the Final Office Action mailed on June 10, 2004. Please amend the above-identified patent application as follows.